



**NIDEC COMPONENTS**

## Features

- Superior circuit protection
- Overcurrent and overvoltage protection
- Blocks surges up to rated limits
- High speed performance
- Small SMT package
- Agency recognition:

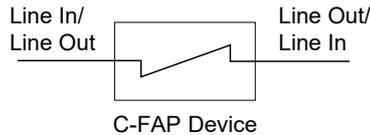
## Applications

- Voice / VDSL cards
- Protection modules and dongles
- Process control equipment
- Test and measurement equipment
- General electronics

# C-FAP-CA Series - C-FAP Fast Acting Protectors

### General Information

The C-FAP-CA Series of NIDEC COMPONENTS C-FAP products are low capacitance single bidirectional high speed protection components, constructed using MOSFET semiconductor technology, and designed to protect against faults caused by short circuits, AC power cross, induction and lightning surges.



### Agency Approval

Description	
UL	File Number: E344793

The C-FAP high speed protector placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics will not be exposed to large voltages or currents during surge events. The C-FAP device is provided in a surface mount DFN package and meets industry standard requirements such as RoHS and Pb Free solder re flow profiles.

### Absolute Maximum Ratings (@ T<sub>A</sub> = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Part Number	Value	Unit
V <sub>imp</sub>	Peak impulse voltage withstand with duration less than 10 ms	C-FAP-CA025-xxx-WH	250	V
		C-FAP-CA040-xxx-WH	400	
		C-FAP-CA050-xxx-WH	500	
		C-FAP-CA065-xxx-WH	650	
		C-FAP-CA085-xxx-WH	850	
V <sub>rms</sub>	Continuous A.C. RMS voltage	C-FAP-CA025-xxx-WH	100	V
		C-FAP-CA040-xxx-WH	200	
		C-FAP-CA050-xxx-WH	250	
		C-FAP-CA065-xxx-WH	300	
		C-FAP-CA085-xxx-WH	425	
T <sub>op</sub>	Operating temperature range		-40 to +125	°C
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C
T <sub>jmax</sub>	Maximum Junction Temperature		+125	°C
ESD	HBM ESD protection per IEC 61000-4-2		±2	kV

\*RoHS Directive 2015/863, Mar. 31, 2015 and Annex.  
 Specifications are subject to change without notice.  
 Customers should verify actual device performance in their specific applications.

# C-FAP-CA Series - C-FAP Fast Acting Protectors

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## Electrical Characteristics (@ T<sub>A</sub> = 25 °C Unless Otherwise Noted)

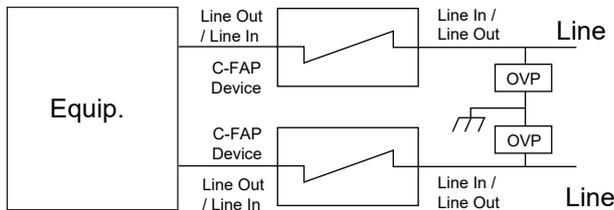
Symbol	Parameter	Part Number	Min.	Typ.	Max.	Unit	
I <sub>trigger</sub>	Current required for the device to go from operating state to protected state	C-FAP-CAxxx-050-WH	50	75	100	mA	
		C-FAP-CAxxx-100-WH	100	150	200		
		C-FAP-CAxxx-200-WH	200	300	400		
		C-FAP-CAxxx-300-WH	300	450	600		
		C-FAP-CAxxx-500-WH	500	750	1000		
R <sub>C-FAP</sub>	Series resistance of the C-FAP device	V <sub>imp</sub> = 250 V I <sub>trigger</sub> (min.) = 50 mA	C-FAP-CA025-050-WH		13.3	15.3	Ω
		V <sub>imp</sub> = 250 V I <sub>trigger</sub> (min.) = 100 mA	C-FAP-CA025-100-WH		7.1	8.2	
		V <sub>imp</sub> = 250 V I <sub>trigger</sub> (min.) = 200 mA	C-FAP-CA025-200-WH		4.2	4.8	
		V <sub>imp</sub> = 250 V I <sub>trigger</sub> (min.) = 300 mA	C-FAP-CA025-300-WH		3.2	3.8	
		V <sub>imp</sub> = 250 V I <sub>trigger</sub> (min.) = 500 mA	C-FAP-CA025-500-WH		2.6	3.0	
		V <sub>imp</sub> = 400 V I <sub>trigger</sub> (min.) = 50 mA	C-FAP-CA040-050-WH		14.3	16.5	
		V <sub>imp</sub> = 400 V I <sub>trigger</sub> (min.) = 100 mA	C-FAP-CA040-100-WH		8.1	9.4	
		V <sub>imp</sub> = 400 V I <sub>trigger</sub> (min.) = 200 mA	C-FAP-CA040-200-WH		5.2	6.0	
		V <sub>imp</sub> = 400 V I <sub>trigger</sub> (min.) = 300 mA	C-FAP-CA040-300-WH		4.3	5.0	
		V <sub>imp</sub> = 400 V I <sub>trigger</sub> (min.) = 500 mA	C-FAP-CA040-500-WH		3.6	4.2	
		V <sub>imp</sub> = 500 V I <sub>trigger</sub> (min.) = 50 mA	C-FAP-CA050-050-WH		15.7	18.0	
		V <sub>imp</sub> = 500 V I <sub>trigger</sub> (min.) = 100 mA	C-FAP-CA050-100-WH		9.5	10.9	
		V <sub>imp</sub> = 500 V I <sub>trigger</sub> (min.) = 200 mA	C-FAP-CA050-200-WH		6.6	7.5	
		V <sub>imp</sub> = 500 V I <sub>trigger</sub> (min.) = 300 mA	C-FAP-CA050-300-WH		5.6	6.5	
		V <sub>imp</sub> = 500 V I <sub>trigger</sub> (min.) = 500 mA	C-FAP-CA050-500-WH		5.0	5.7	
		V <sub>imp</sub> = 650 V I <sub>trigger</sub> (min.) = 50 mA	C-FAP-CA065-050-WH		17.7	20.3	
		V <sub>imp</sub> = 650 V I <sub>trigger</sub> (min.) = 100 mA	C-FAP-CA065-100-WH		11.5	13.2	
		V <sub>imp</sub> = 650 V I <sub>trigger</sub> (min.) = 200 mA	C-FAP-CA065-200-WH		8.6	9.8	
		V <sub>imp</sub> = 650 V I <sub>trigger</sub> (min.) = 300 mA	C-FAP-CA065-300-WH		7.6	8.8	
		V <sub>imp</sub> = 650 V I <sub>trigger</sub> (min.) = 500 mA	C-FAP-CA065-500-WH		7.0	8.0	
		V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.) = 50 mA	C-FAP-CA085-050-WH		21.4	24.5	
		V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.) = 100 mA	C-FAP-CA085-100-WH		15.2	17.4	
		V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.) = 200 mA	C-FAP-CA085-200-WH		12.3	14.0	
		V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.) = 300 mA	C-FAP-CA085-300-WH		11.3	13.0	
V <sub>imp</sub> = 850 V I <sub>trigger</sub> (min.) = 500 mA	C-FAP-CA085-500-WH		10.7	12.2			
t <sub>block</sub>	Time for the device to go from normal operating state to protected state				1	μs	
I <sub>Q</sub>	Current through the triggered C-FAP device with 50 Vdc circuit voltage		0.25	0.50	1.00	mA	
V <sub>reset</sub>	Voltage below which the triggered C-FAP device will transition to normal operating state		12	16	20	V	
R <sub>th(j-l)</sub>	Junction to package pads - FR4 using recommended pad layout			98		°C/W	
R <sub>th(j-l)</sub>	Junction to package pads - FR4 using heat sink on board (6 cm <sup>2</sup> ) (1 in <sup>2</sup> )			40		°C/W	

# C-FAP-CA Series - C-FAP Fast Acting Protectors

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## Reference Application

The C-FAP devices are general use protectors used in a wide variety of applications. The maximum voltage rating of the C-FAP device should never be exceeded. Where necessary, an OVP should be employed to limit the maximum voltage. A cost-effective protection solution combines NIDEC COMPONENTS C-FAP protection devices with a pair of Bourns® MOVs. For bandwidth sensitive applications, a Bourns® GDT may be substituted for the MOV.



## Basic C-FAP Operation

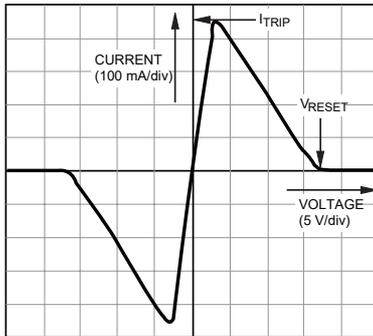
The C-FAP device, constructed using MOSFET semiconductor technology, placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics are not exposed to large voltages or currents during surge events. The C-FAP device operates in approximately 1  $\mu$ s - once line current exceeds the C-FAP device's trigger current  $I_{TRIP}$ . When operated, the C-FAP device restricts line current to less than 1 mA typically. When operated, the C-FAP device will block all voltages including the surge up to rated limits.

After the surge, the C-FAP device resets when the voltage across the C-FAP device falls to the  $V_{RESET}$  level. The C-FAP device will automatically reset on lines which have no DC bias or have DC bias below  $V_{RESET}$  (such as unpowered signal lines).

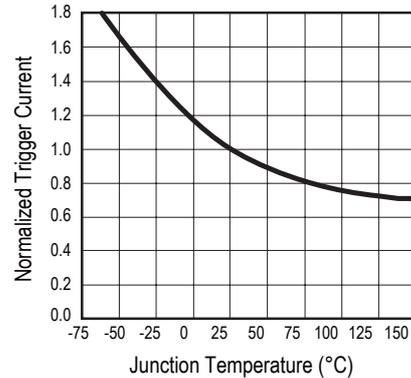
If the line has a normal DC bias above  $V_{RESET}$ , the voltage across the C-FAP device may not fall below  $V_{RESET}$  after the surge. In such cases, special care needs to be taken to ensure that the C-FAP device will reset, with software monitoring as one method used to accomplish this. NIDEC COMPONENTS application engineers can provide further assistance.

## Performance Graphs

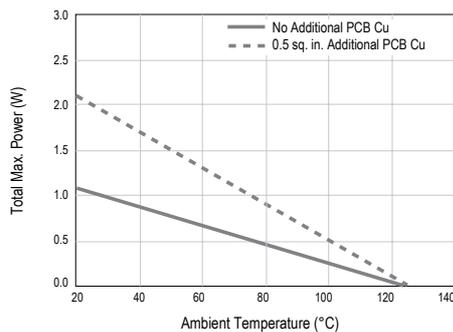
### Typical V-I Characteristics (C-FAP-CA050-300-WH)



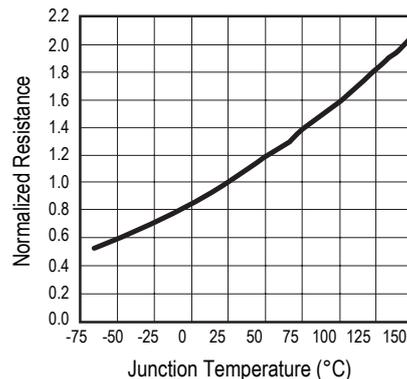
### Typical Trigger Current vs. Temperature



### Power Derating Curve

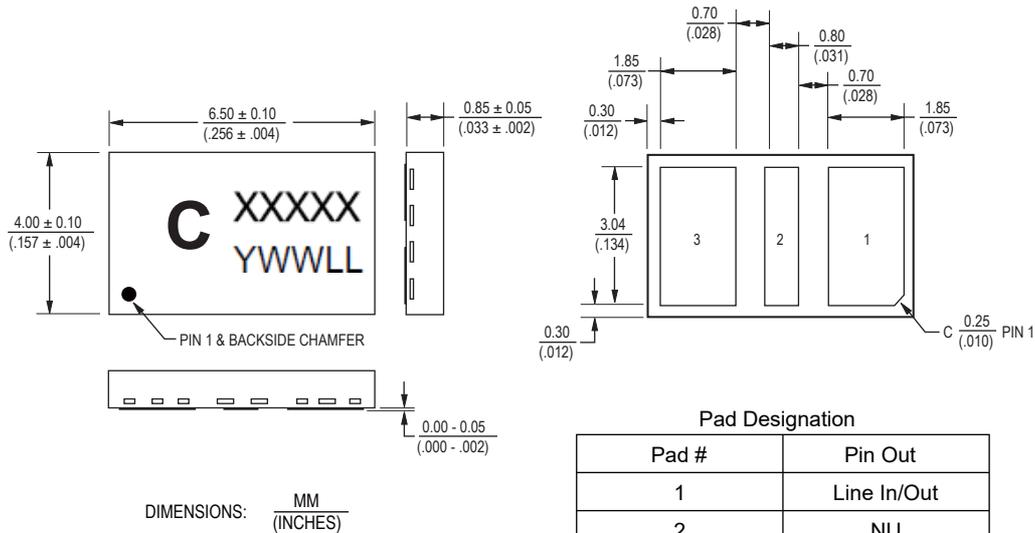


### Typical Resistance vs. Temperature



Specifications are subject to change without notice. Customers should verify actual device performance in their specific applications.

## Product Dimensions



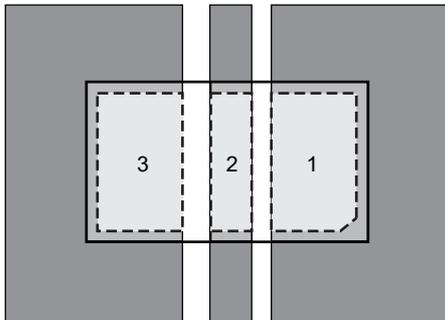
Pad Designation

Pad #	Pin Out
1	Line In/Out
2	NU
3	Line Out/In

Note. Unless otherwise specified, tolerance ; ±0.10 (unit : mm)

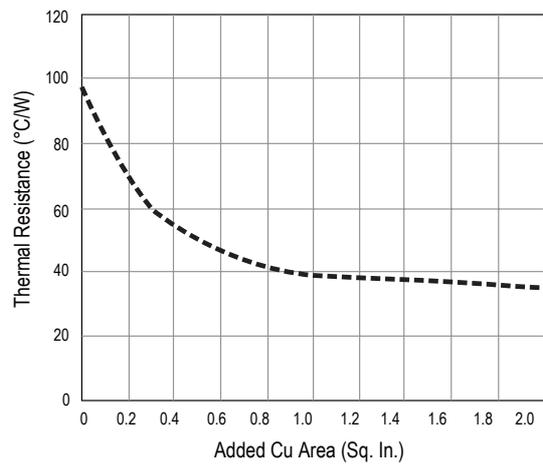
## Recommended Pad Layout

C-FAP protectors have matte-tin termination finish. The suggested layout should use Non-Solder Mask Define (NSMD). The recommended stencil thickness is 0.10-0.12 mm (.004-.005 in.) with a stencil opening size 0.025 mm (.0010 in.) less than the device pad size. As when heat sinking any power device, it is recommended that wherever possible, extra PCB copper area is allowed. For minimum parasitic capacitance, do not allow any signal, ground or power signals beneath any of the pads of the device.



Dark grey areas show added PCB copper area for better thermal resistance.

## Thermal Resistance vs Additional PCB Cu Area

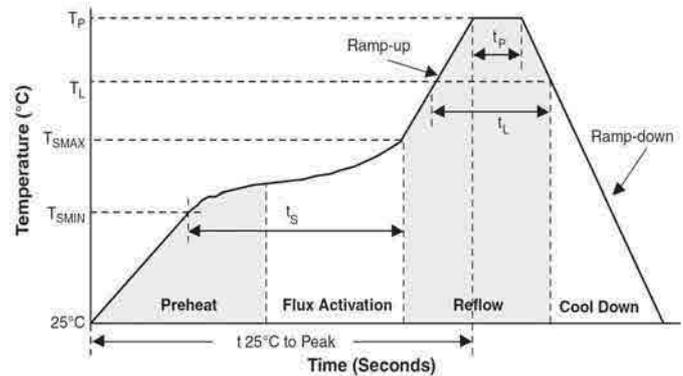


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## Reflow Profile

Reflow Profile	Pb-Free Assembly
Average Ramp-Up Rate (T <sub>smax</sub> to T <sub>p</sub> )	3 °C/sec. max.
Preheat <ul style="list-style-type: none"> <li>- Temperature Min. (T<sub>smin</sub>)</li> <li>- Temperature Max. (T<sub>smax</sub>)</li> <li>- Time (t<sub>smin</sub> to t<sub>smax</sub>)</li> </ul>	150 °C 200 °C 60-180 sec.
Time maintained above: <ul style="list-style-type: none"> <li>- Temperature (T<sub>L</sub>)</li> <li>- Time (t<sub>L</sub>)</li> </ul>	217 °C 60-150 sec.
Peak/Classification Temperature (T <sub>p</sub> )	260 °C
Time within 5 °C of Actual Peak Temp. (t <sub>p</sub> )	20-40 sec.
Ramp-Down Rate	6 °C/sec. max.
Time 25 °C to Peak Temperature	8 min. max.



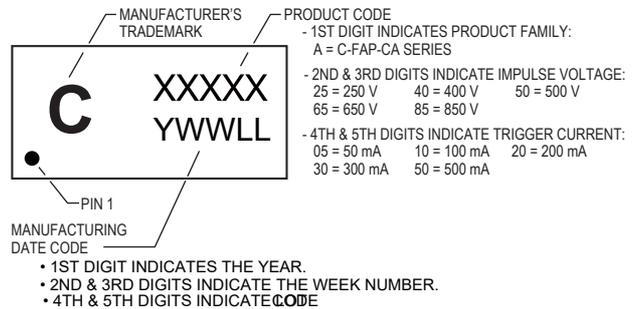
## How to Order

C-FAP - CA 085 - 500 - WH

C-FAP Product	_____	_____	_____	_____	_____
Series	_____	_____	_____	_____	_____
Impulse Voltage Rating	_____	_____	_____	_____	_____
Trigger Current	_____	_____	_____	_____	_____
Hold to Trip Ratio Suffix	_____	_____	_____	_____	_____
Package Suffix	_____	_____	_____	_____	_____

CA = Bi-Series  
 025 = 250 V  
 040 = 400 V  
 050 = 500 V  
 065 = 650 V  
 085 = 850 V  
 050 = 50 mA  
 100 = 100 mA  
 200 = 200 mA  
 300 = 300 mA  
 500 = 500 mA  
 W = Hold to Trip Ratio  
 H = DFN Package

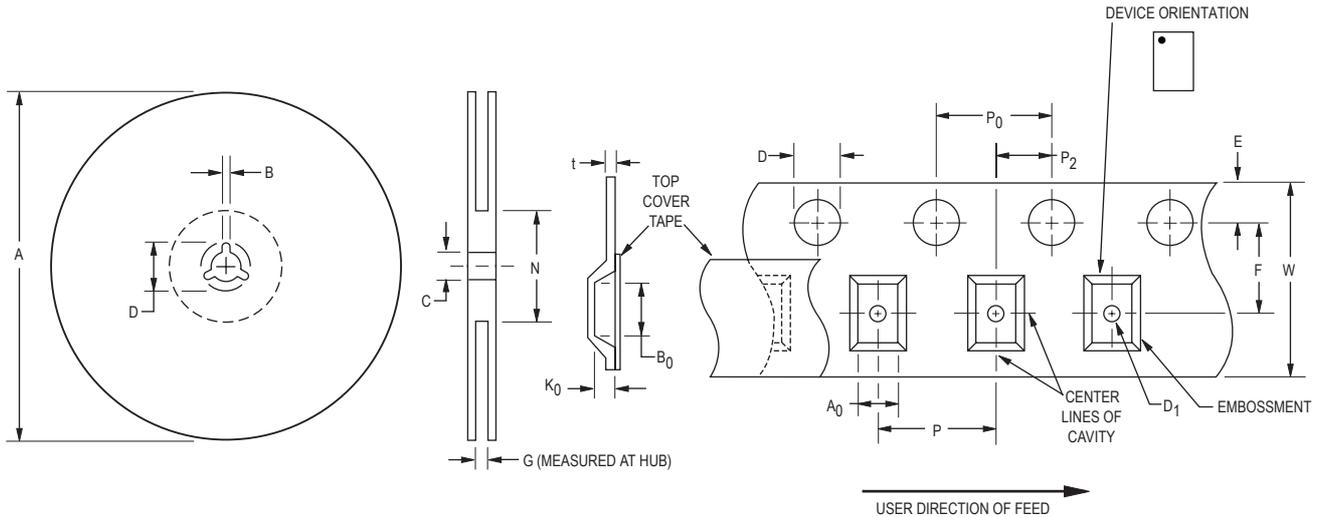
## Typical Part Marking



# C-FAP-CA Series - C-FAP Fast Acting Protectors

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## Packaging Specifications



QUANTITY: 3000 PIECES PER REEL

A		B		C		D		G	N
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Ref.	Ref.
326	330	1.5	2.5	12.8	13.5	20.2	-	16.5	102
(12.835)	(13.002)	(.059)	(.098)	(.504)	(.531)	(.795)		(.650)	(4.016)

A0		B0		D		D1		E		F	
Min.	Max.										
4.3	4.5	6.7	6.9	1.5	1.6	1.5	-	1.65	1.85	7.4	7.6
(.169)	(.177)	(.264)	(.272)	(.059)	(.063)	(.059)		(.065)	(.073)	(.291)	(.299)
K0		P		P0		P2		t		W	
Min.	Max.										
1.0	1.2	7.9	8.1	3.9	4.1	1.9	2.1	0.25	0.35	15.7	16.3
(.039)	(.047)	(.311)	(.319)	(.159)	(.161)	(.075)	(.083)	(.010)	(.014)	(.618)	(.642)

DIMENSIONS:  $\frac{\text{MM}}{\text{(INCHES)}}$

### Revision History

Date	Rev.	Reason
10/12/2010	A	Initial issue
05/15/2012	A1	Updated Performance Graphs and Packaging Specifications
07/16/2014	A2	Tolerance was added to the product size.
02/13/2017	B	Change marking.
04/03/2023	C	Change our company name.

Revision : C  
Issue date : 04/03/2023

C-FAP-CA SERIES

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